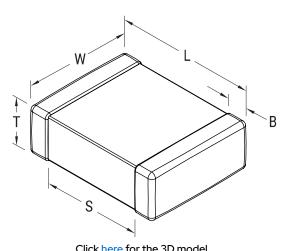


C0603X301MATAC7411

SMD Comm X8G HT150C Flex, Ceramic, 300 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm





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Dimensions			
Chip Size	0603		
L	1.6mm +/-0.17mm		
W	0.8mm +/-0.15mm		
Т	0.8mm +/-0.15mm		
S	0.4mm MIN		
В	0.45mm +/-0.15mm		

Packaging Specifications		
Packaging	T&R, 330mm, Paper Tape	
Packaging Quantity	15000	

General Information				
Series	SMD Comm X8G HT150C Flex			
Style	SMD Chip			
Description	SMD, MLCC, High Temperature, Ultra-Stable			
Features	High Temperature, Ultra-Stable			
RoHS	Yes			
Termination	Flexible Termination			
Marking	No			
AEC-Q200	No			
Typical Component Weight	4.6 mg			
Shelf Life	78 Weeks			
MSL	1			

Specifications				
Capacitance	300 pF			
Measurement Condition	1 MHz 1.0Vrms			
Tolerance	20%			
Voltage DC	250 VDC			
Dielectric Withstanding Voltage	625 VDC			
Temperature Range	-55/+150°C			
Temp. Coefficient	X8G			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms			
Dissipation Factor	0.1% 1 MHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours			
Insulation Resistance	100 GOhms			

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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